

# Product End-of-Life Disassembly Instructions

Marketing Name / Model [List multiple models if applicable.]	Product Category
HP Omni <sup>100</sup> PC	Integrated PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	10
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	4
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB / PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
screw driver	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Place the system
2. Disassemble hinge cover & access door
3. Disassemble stand
4. Remove ODD&TOP Perf
5. Disassemble rear cover
6. Disassemble HDD
7. Disassemble CPU&I/O Shielding
8. Disassemble speaker
9. Disassemble stand support
10. Disassemble CPU H/S
11. Disassemble FAN
12. Unplug cable
13. Disassemble WLAN
14. Disassemble INVERTER
15. Disassemble MB
16. Remove power switch card
17. Disassemble webcam & antenna cable
18. Separate BASE pan& bezel

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).





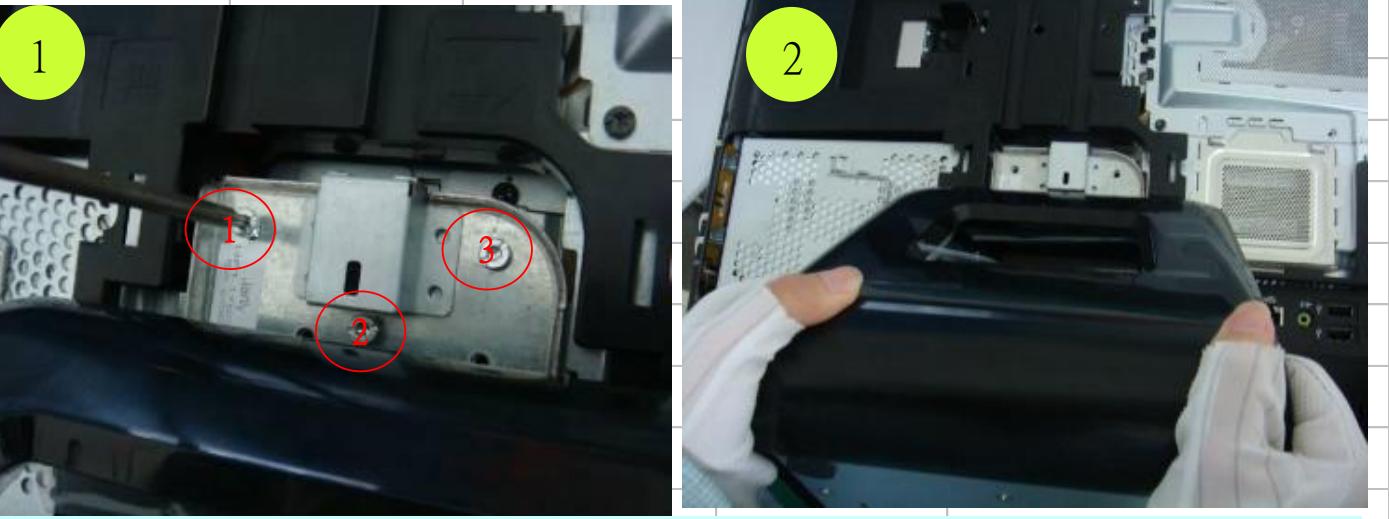
Do cosmetic check then place unit on work table.

19. Disassemble hinge cover & access door



Disassemble hinge cover & R/L access door.

20. Disassemble stand

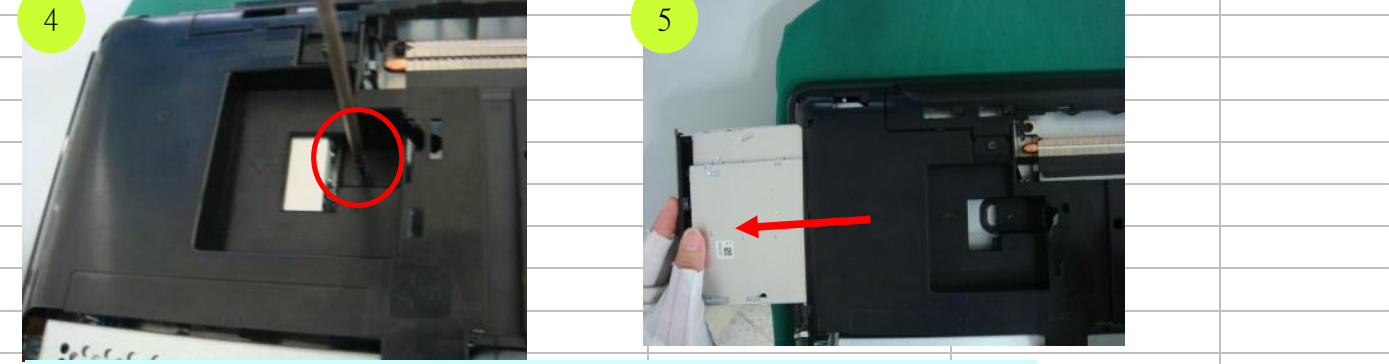


Remove 3 screws for fixing stand.  
Place stand to specified area.

21. Remove ODD&TOP Perf



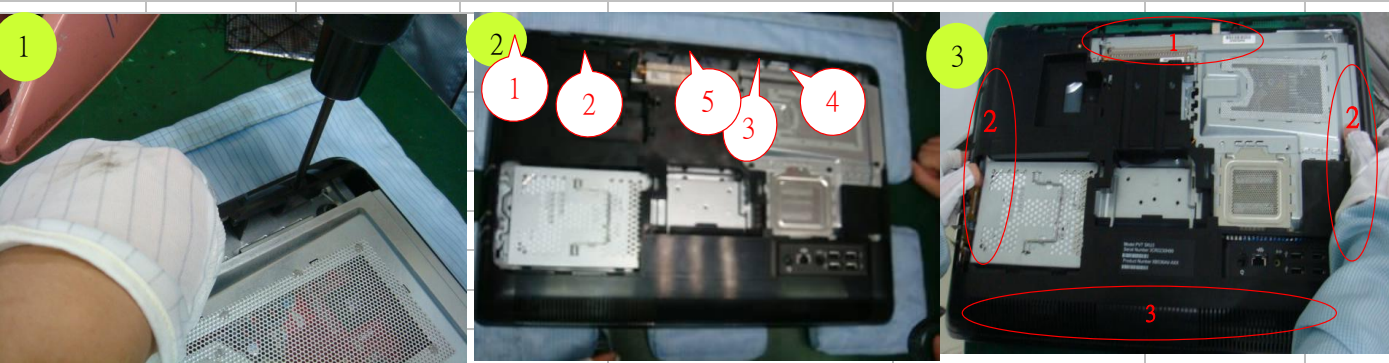
Remove 2 screws for fixing top perf.  
Take top perf.



Remove one screw for fixing ODD, Put ODD to specified area.

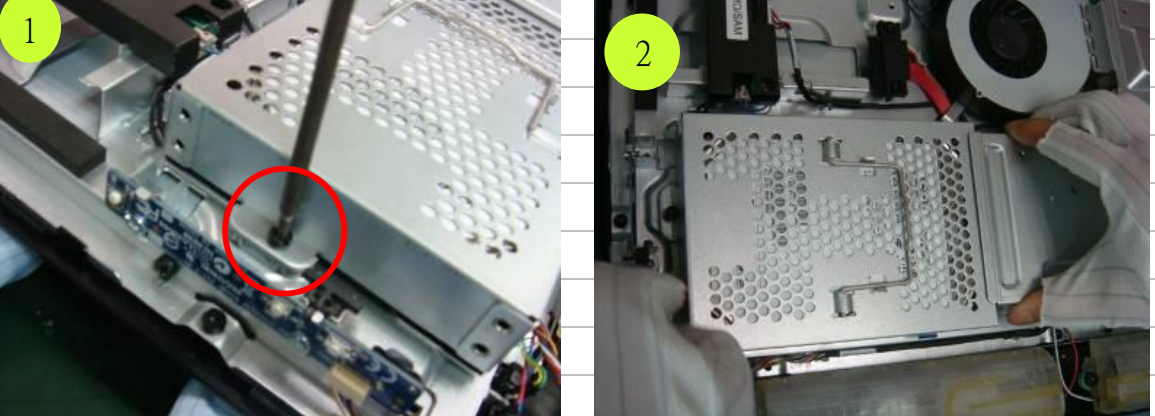
22. Disassemble rear cover





Remove 5 screws for locking rear cover. Remove rear cover as sequence shows in pic3

6) Disassemble HDD



1.Remove 1pcs screw for fixing HDD

Hold unit with right hand, remove HDD with left hand, Put HDD to specified

7) Disassemble CPU&I/O Shielding



Remove 7 screws for fixing CPU shielding & I/O

Remove CPU shielding.

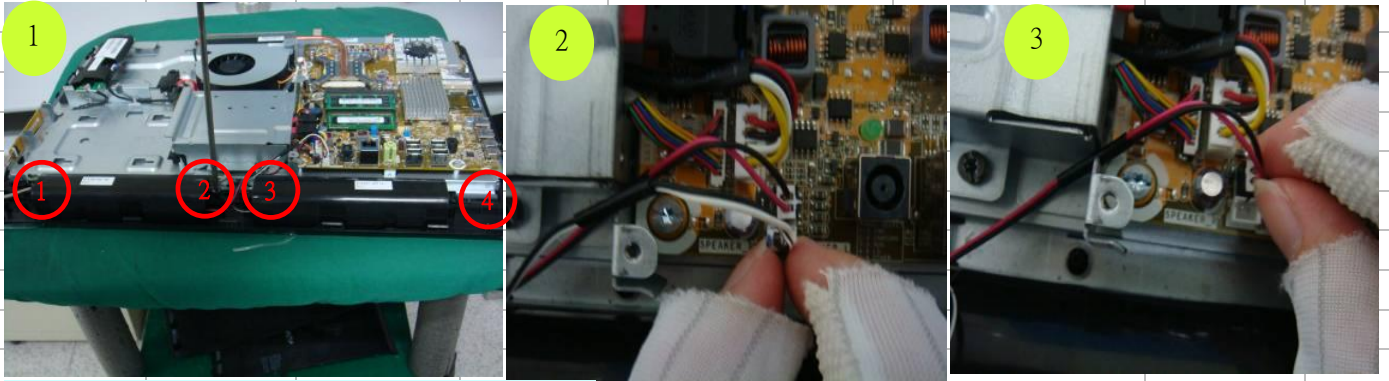


Remove DDR cover.



Remove I/O shielding.

8) Disassemble speaker



Remove 4pcs screws for fixing speaker. Unplug speaker cable.

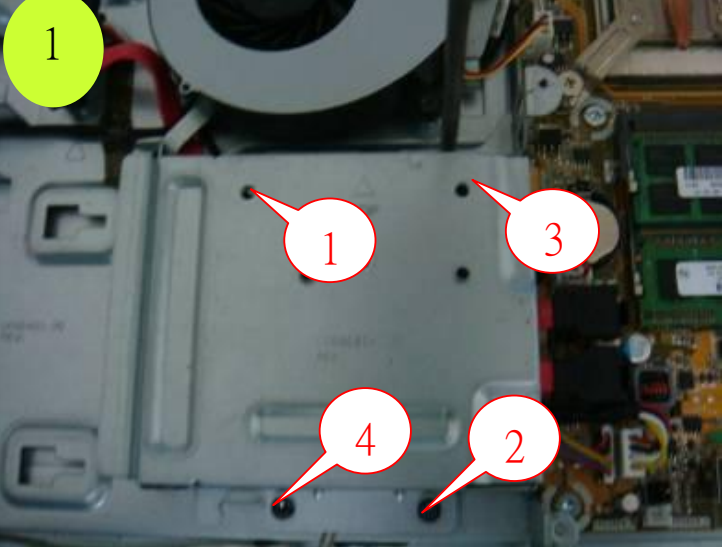


Take R/L speaker out.

9) Disassemble stand support



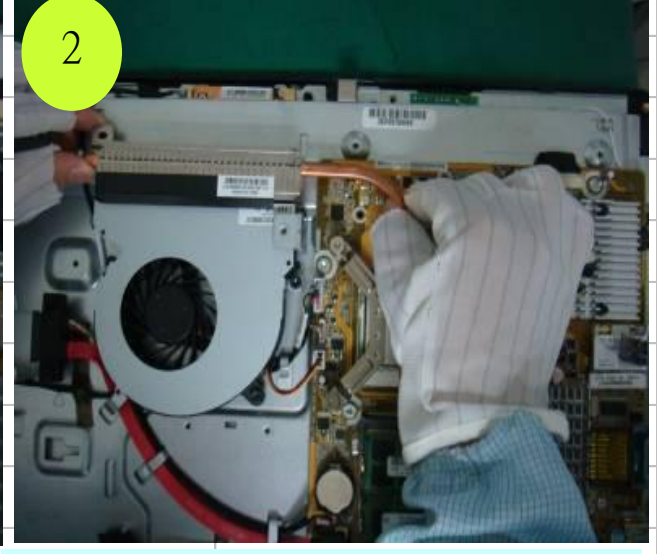
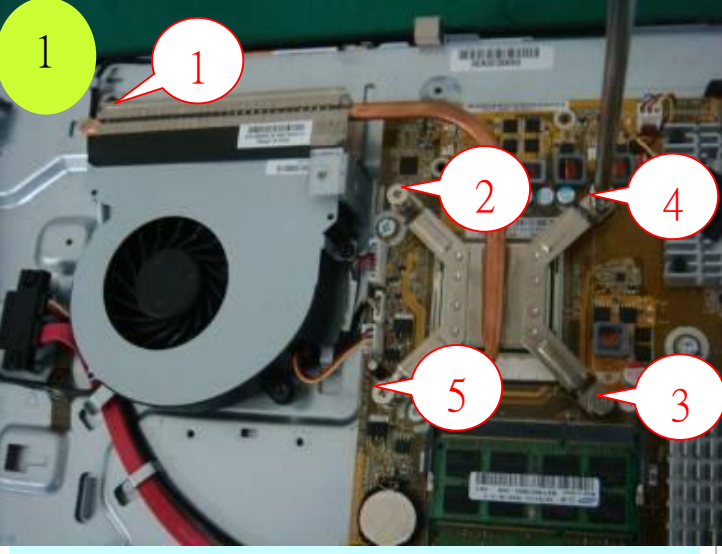




Remove 4pcs screws.

Take stand support out.

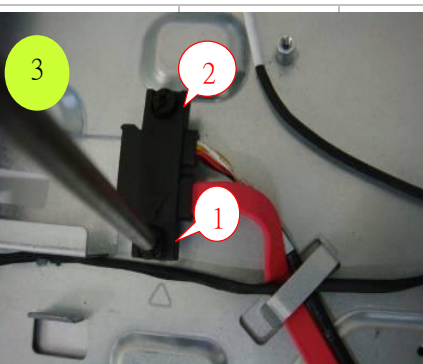
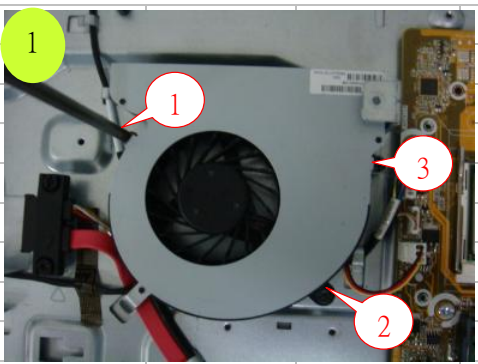
10) Disassemble CPU H/S



Remove 5pcs screws.

Take CPU H/S out.

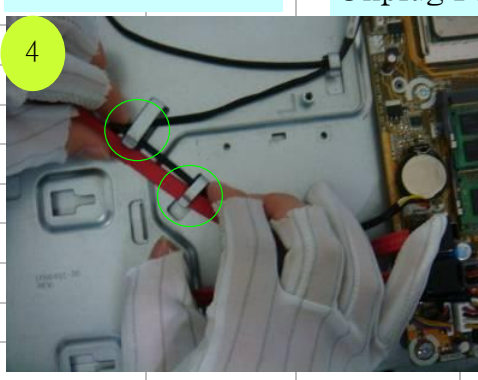
11) Disassemble FAN



Remove 3 screws.

Unplug Fan cable, take fan

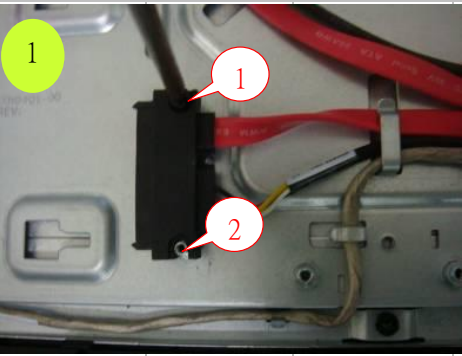
Remove 2 screws for fixing ODD SATA cable.



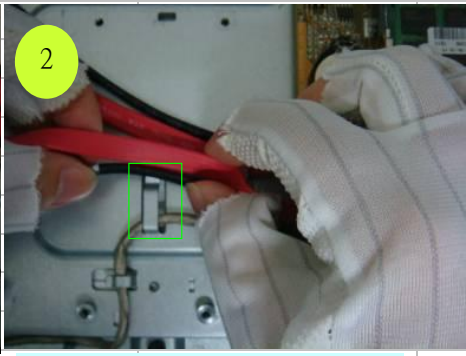
Route ODD SATA+Power cable out of hook.

12) Unplug cable

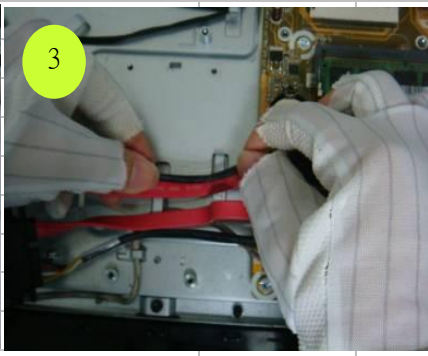




Remove 2pcs screws for fixing HDD SATA & Power cable.



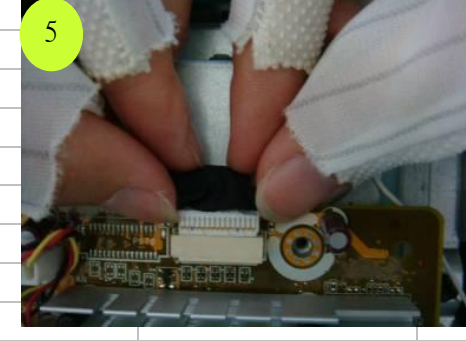
Route HDD SATA & power cable out of hook.



Route ODD SATA & Power cable out of hook.



Unplug HDD Power cable, HDD SATA cable, ODD SATA cable, ODD Power cable, power switch cable.



Unplug LVDS cable.

### 13) Disassemble WLAN



Remove tape.



Pull antenna cable out.



Remove 2pcs screws.



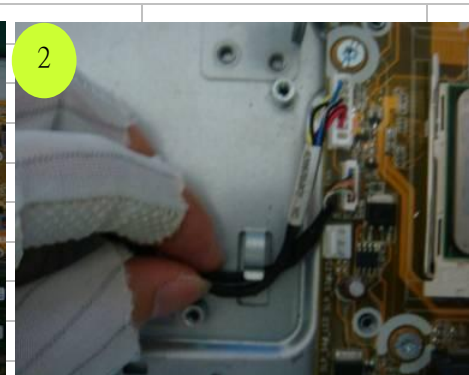
Pull WLAN card out.



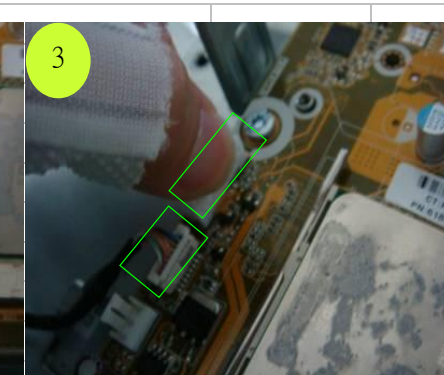
### 14) Disassemble INVERTER



Route inverter cable out of hook.



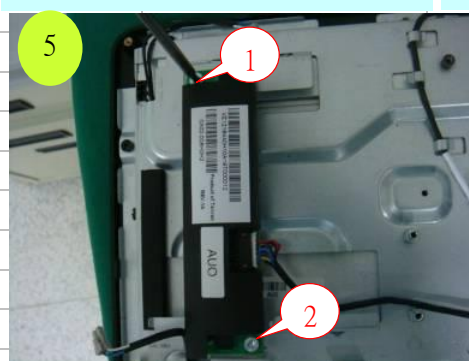
Route inverter cable & camera cable out of hook.



Unplug inverter cable & camera cable from MB side.



Unplug inverter cable.



Remove 2pcs screws for fixing inverter.



Take inverter out.

### 15) Disassemble MB





Remove 6pcs screws for locking      Remove MB.      Remove tape.

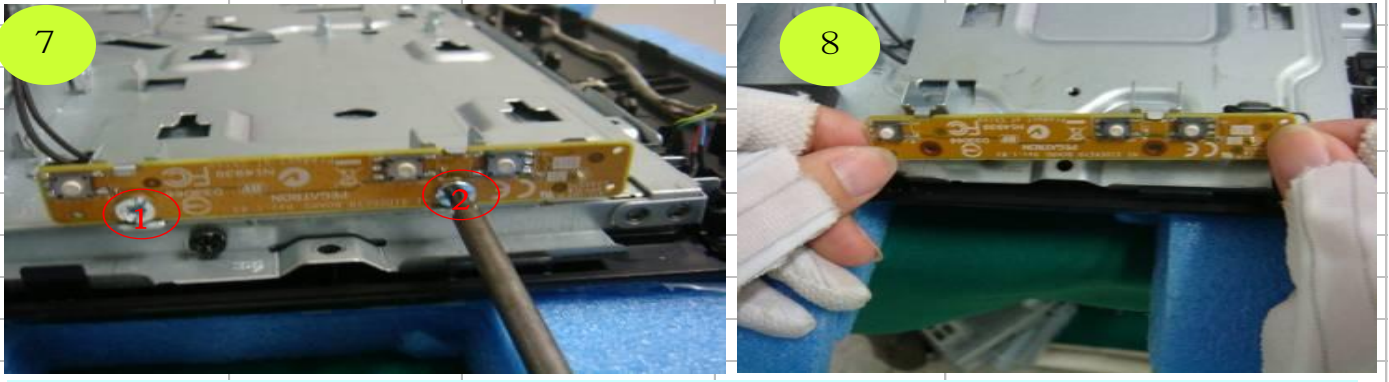
16) Remove power switch card



Tear pad off.      Route power switch cable out of hook.



Route camera cable out of hook. Route antenna cable out of hook.      Unplug power switch cable.



Remove 2pcs screws for locking power switch card.

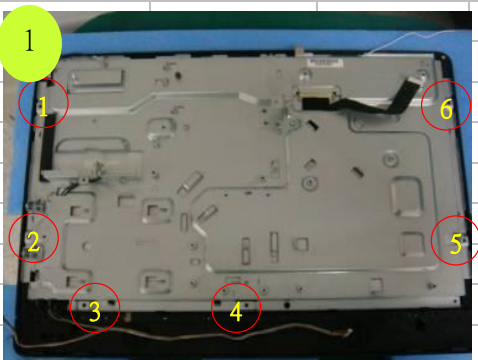
17) Disassemble webcam & antenna cable



Remove 2pcs screws for fixing webcam.      Take webcam out.      Rip antenna

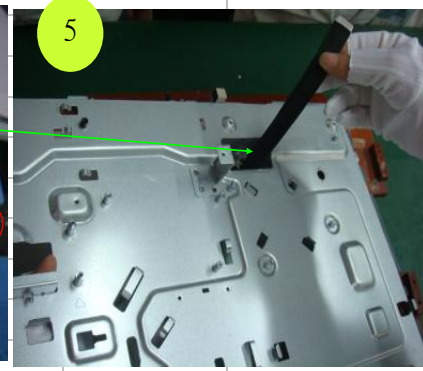
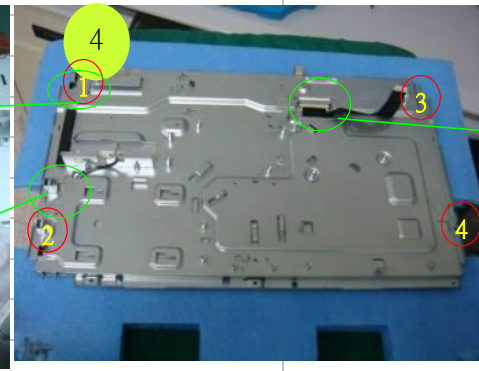
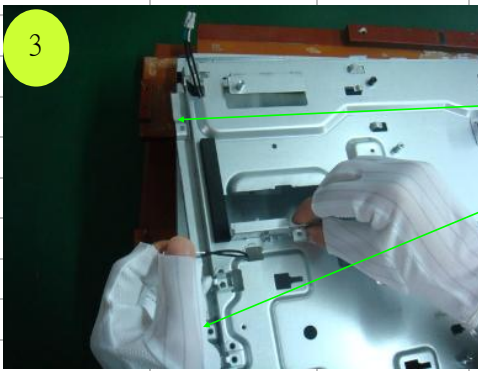
18) Separate BASE pan& bezel





Remove 6 screws.

Separate base pan & front bezel.



Remove 4 screws for locking base pan & LCD. Separate LCD & base pan.